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# 312.5 MHz LVPECL Clock Generator

#### **Features**

■ One LVPECL output pair

■ Output frequency: 312.5 MHz

■ External crystal frequency: 25 MHz

■ Low RMS phase jitter at 312.5 MHz, using 25-MHz crystal (1.875 MHz to 20 MHz): 0.3 ps (typical)

■ Pb-free 8-pin TSSOP package

■ Supply voltage: 3.3 V or 2.5 V

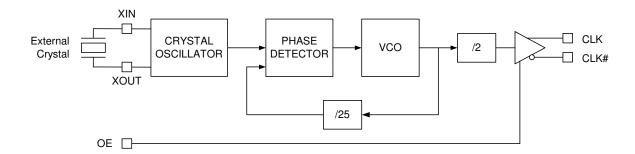
■ Commercial and industrial temperature ranges

### **Functional Description**

The CY2XP311 is a PLL (phase locked loop) based high performance clock generator. It is optimized to generate 10 GB Ethernet, SONET, and other high performance clock frequencies. It also produces an output frequency that is 12.5 times the crystal frequency. It uses Cypress's low noise VCO technology to achieve 0.3 ps typical RMS phase jitter, which meets both 10 GB Ethernet and SONET jitter requirements. The CY2XP311 has a crystal oscillator interface input and one LVPECL output pair.

For a complete list of related documentation, click here.

### **Logic Block Diagram**





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## **Pinouts**

Figure 1. 8-pin TSSOP pinout

VDD	1	8 VDD
VSS <u></u>	2	7 CLK
XOUT	3	6 CLK#
XIN	4	5 OE

## **Pin Definitions**

8-pin TSSOP

Pin Number	Pin Name	I/O Type	Description	
1, 8	VDD	Power	3.3 V or 2.5 V power supply.	
2	VSS	Power	Ground	
3, 4	XOUT, XIN	XTAL output and input	Parallel resonant crystal interface	
5	OE	CMOS input	Output enable. When HIGH, the output is enabled. When LOW, the output high impedance	
6, 7	CLK#, CLK	LVPECL output	Differential clock output	

# Frequency Table

Inj	Output Frequency (MHz)	
Crystal Frequency (MHz)	PLL Multiplier Value	Output Frequency (WHZ)
25	12.5	312.5



#### **Absolute Maximum Conditions**

Parameter	Description	Conditions	Min	Max	Unit
$V_{DD}$	Supply voltage	-	-0.5	4.4	V
V <sub>IN</sub> <sup>[1]</sup>	Input voltage, DC	Relative to V <sub>SS</sub>	-0.5	V <sub>DD</sub> + 0.5	٧
T <sub>S</sub>	Temperature, storage	Non operating	-65	150	°C
T <sub>J</sub>	Temperature, junction	-	-	135	°C
ESD <sub>HBM</sub>	ESD protection, human body model	JEDEC STD 22-A114-B	2000	-	V
UL-94	Flammability rating	At 1/8 in.	V-0		
$\Theta_{JA}^{[2]}$ Thermal resistance, junction to		0 m/s airflow	10	00	°C/W
	ambient	1 m/s airflow	g	)1	
		2.5 m/s airflow	8	37	

## **Operating Conditions**

Parameter	Description		Max	Unit
$V_{DD}$	3.3 V supply voltage	3.135	3.465	V
	2.5 V supply voltage	2.375	2.625	V
T <sub>A</sub>	Ambient temperature, commercial		70	°C
	Ambient temperature, industrial		85	°C
T <sub>PU</sub>	Power up time for all $\mbox{\rm V}_{\mbox{\scriptsize DD}}$ to reach minimum specified voltage (ensure power ramps is monotonic)	0.05	500	ms

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Notes
 The voltage on any input or I/O pin cannot exceed the power pin during power up.
 Simulated using Apache Sentinel TI software. The board is derived from the JEDEC multilayer standard. It measures 76 x 114 x 1.6 mm and has 4-layers of copper (2/1/1/2 oz.). The internal layers are 100% copper planes, while the top and bottom layers have 50% metalization. No vias are included in the model.



## **DC Electrical Characteristics**

Parameter	Description	Test Conditions	Min	Тур	Max	Unit
I <sub>DD</sub>	Operating supply current with output unterminated	V <sub>DD</sub> = 3.465 V, OE = V <sub>DD</sub> , output unterminated	_	_	125	mA
		V <sub>DD</sub> = 2.625 V, OE = V <sub>DD</sub> , output unterminated	_	-	120	mA
I <sub>DDT</sub>	Operating supply current with output terminated	V <sub>DD</sub> = 3.465 V, OE = V <sub>DD</sub> , output terminated	_	-	150	mA
		V <sub>DD</sub> = 2.625 V, OE = V <sub>DD</sub> , output terminated	_	-	145	mA
V <sub>OH</sub>	LVPECL output high voltage	$V_{DD} = 3.3 \text{ V or } 2.5 \text{ V},$ $R_{TERM} = 50 \Omega \text{ to } V_{DD} - 2.0 \text{ V}$	V <sub>DD</sub> – 1.15	_	V <sub>DD</sub> – 0.75	٧
V <sub>OL</sub>	LVPECL output low voltage	$V_{DD}$ = 3.3 V or 2.5 V, $R_{TERM}$ = 50 $\Omega$ to $V_{DD}$ – 2.0 V	V <sub>DD</sub> – 2.0	-	V <sub>DD</sub> – 1.625	V
V <sub>OD1</sub>	LVPECL peak-to-peak output voltage swing	$V_{DD} = 3.3 \text{ V or } 2.5 \text{ V},$ $R_{TERM} = 50 \Omega \text{ to } V_{DD} - 2.0 \text{ V}$	600	-	1000	mV
V <sub>OD2</sub>	LVPECL output voltage swing (V <sub>OH</sub> - V <sub>OL</sub> )	$V_{DD}$ = 2.5 V, R <sub>TERM</sub> = 50 $\Omega$ to $V_{DD}$ – 1.5 V	500	_	1000	mV
V <sub>OCM</sub>	LVPECL output common mode voltage (V <sub>OH</sub> + V <sub>OL</sub> )/2	$V_{DD}$ = 2.5 V, R <sub>TERM</sub> = 50 $\Omega$ to $V_{DD}$ – 1.5 V	1.2	_	_	٧
I <sub>OZ</sub>	LVPECL output leakage current	Output off, OE = V <sub>SS</sub>	-35	_	35	μА
V <sub>IH</sub>	Input high voltage, OE Pin	-	$0.7 \times V_{DD}$	_	$V_{DD} + 0.3$	V
V <sub>IL</sub>	Input low voltage, OE Pin	-	-0.3	_	0.3 × V <sub>DD</sub>	V
I <sub>IH</sub>	Input high current, OE Pin	OE = V <sub>DD</sub>	_	_	115	μΑ
I <sub>IL</sub>	Input low current, OE Pin	OE = V <sub>SS</sub>	-50	_	-	μΑ
C <sub>IN</sub> [3]	Input capacitance, OE Pin	_	_	15	_	pF
C <sub>INX</sub> [3]	Pin capacitance, XIN & XOUT	_	_	4.5	-	pF

Notes
3. Not 100% tested, guaranteed by design and characterization.



## **AC Electrical Characteristics**

Parameter [4]	Description	Conditions	Min	Тур	Max	Unit
F <sub>OUT</sub>	Output frequency		_	312.5	-	MHz
T <sub>R</sub> , T <sub>F</sub> <sup>[5]</sup>	Output rise or fall time	20% to 80% of full output swing	_	0.5	1.0	ns
T <sub>Jitter(<math>\phi</math>)</sub> <sup>[6]</sup>	RMS phase jitter (random)	312.5 MHz, (1.875 to 20 MHz)	-	0.3	-	ps
T <sub>DC</sub> <sup>[7]</sup>	Output duty cycle	Measured at zero crossing point	45	-	55	%
T <sub>OHZ</sub>	Output disable time	Time from falling edge on OE to stopped outputs (Asynchronous)	_	_	100	ns
T <sub>OE</sub>	Output enable time	Time from rising edge on OE to outputs at a valid frequency (Asynchronous)	_	_	100	ns
T <sub>LOCK</sub>	Startup time	Time for CLK to reach valid frequency measured from the time $V_{DD} = V_{DD}(min.)$	_	_	5	ms

## **Recommended Crystal Specifications**

Parameter [8]	Description	Min	Max	Unit
Mode	e of Oscillation Fu		Fundamental	
F	Frequency	25	25	MHz
ESR	Equivalent Series Resistance		50	Ω
C <sub>S</sub>	Shunt Capacitance	_	7	pF

- Notes
  4. Not 100% tested, guaranteed by design and characterization.
  5. Refer to Figure 5 on page 7.
  6. Refer to Figure 6 on page 7.
  7. Refer to Figure 7 on page 8.
  8. Characterized using an 18 pF parallel resonant crystal.



#### **Parameter Measurements**

Figure 2. 3.3 V Output Load AC Test Circuit

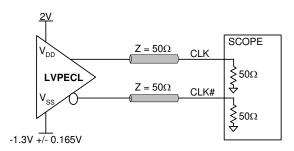


Figure 3. 2.5 V Output Load AC Test Circuit

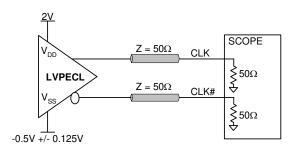


Figure 4. Output DC Parameters

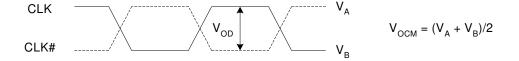


Figure 5. Output Rise and Fall Time

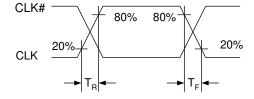


Figure 6. RMS Phase Jitter



## Parameter Measurements (continued)

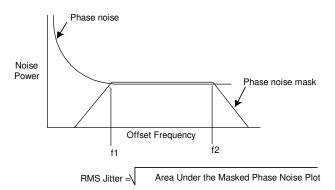


Figure 7. Output Duty Cycle

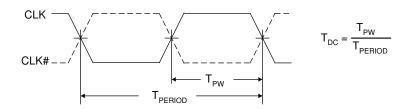
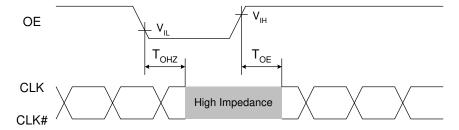


Figure 8. Output Enable Timing





#### **Application Information**

#### **Power Supply Filtering Techniques**

As in any high speed analog circuitry, noise at the power supply pins can degrade performance. To achieve optimum jitter performance, use good power supply isolation practices. Figure 9 illustrates a typical filtering scheme. 0.01 to 0.1  $\mu F$  ceramic chip capacitors are located close to the VDD pins to provide a short and low impedance AC path to ground. A 1 to 10  $\mu F$  ceramic or tantalum capacitor is located in the general vicinity of this device and may be shared with other devices. An acceptable alternative power supply configuration is shown in Figure 10.

Figure 9. Power Supply Filtering

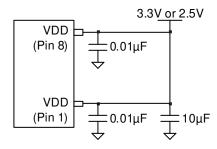
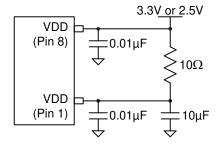


Figure 10. Alternative Power Supply Filtering

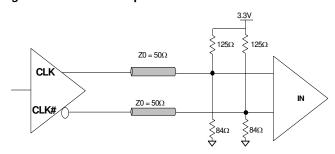


#### **Termination for LVPECL Output**

The CY2XP311 implements its LVPECL driver with a current steering design. For proper operation, it requires a 50 ohm dc termination on each of the two output signals. For 3.3 V operation, this data sheet specifies output levels for termination to  $V_{DD}$ =2.0 V. This same termination voltage can also be used

for  $V_{DD}=2.5~V$  operation, or it can be terminated to  $V_{DD}-1.5~V$ . Note that it is also possible to terminate with 50 ohms to ground  $(V_{SS})$ , but the high and low signal levels differ from the data sheet values. Termination resistors are best located close to the destination device. To avoid reflections, trace characteristic impedance  $(Z_0)$  should match the termination impedance. Figure 11 shows a standard termination scheme.

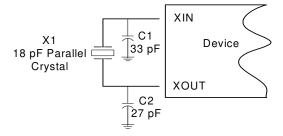
Figure 11. LVPECL Output Termination



#### **Crystal Input Interface**

The CY2XP311 is characterized with 18 pF parallel resonant crystals. The capacitor values shown in Figure 12 are determined using a 25 MHz 18 pF parallel resonant crystal and are chosen to minimize the ppm error. Note that the optimal values for C1 and C2 depend on the parasitic trace capacitance and are therefore layout dependent.

Figure 12. Crystal Input Interface

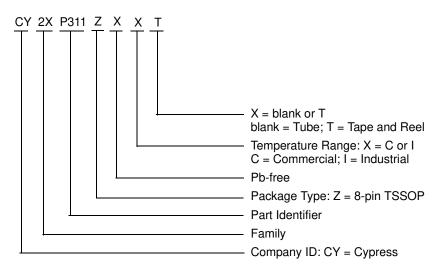




## **Ordering Information**

Part Number	Package Type	Product Flow
CY2XP311ZXI	8-pin TSSOP	Industrial, -40 °C to 85 °C
CY2XP311ZXIT	8-pin TSSOP – Tape and Reel	Industrial, -40 °C to 85 °C

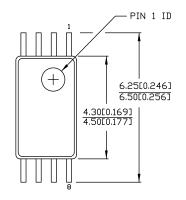
#### **Ordering Code Definitions**





## **Package Drawing and Dimensions**

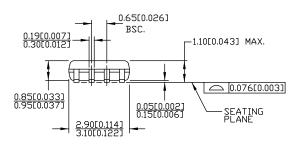
Figure 13. 8-pin TSSOP (4.40 mm Body) Package Outline, 51-85093

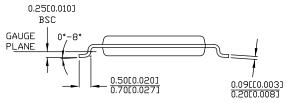


DIMENSIONS IN MM[INCHES]  $\underline{\text{MIN.}}$  MAX.

REFERENCE JEDEC MO-153

PART #		
Z08.173	STANDARD PKG.	
ZZ08.173	LEAD FREE PKG.	





51-85093 \*E



## **Acronyms**

Acronym	Description		
CLKOUT	Clock Output		
CMOS	Complementary Metal Oxide Semiconductor		
DPM	Die Pick Map		
EPROM	Erasable Programmable Read Only Memory		
LVDS	Low-Voltage Differential Signalling		
LVPECL	Low-Voltage Positive Emitter Coupled Logic		
NTSC	National Television System Committee		
OE	Output Enable		
PAL	Phase Alternate Line		
PD	Power Down		
PLL	Phase Locked Loop		
TTL	Transistor-Transistor Logic		

## **Document Conventions**

#### **Units of Measure**

Symbol	Unit of Measure			
°C	degree Celsius			
kHz	kilohertz			
kΩ	kilohm			
MHz	megahertz			
ΜΩ	megaohm			
μΑ	microampere			
μs	microsecond			
μV	microvolt			
μVrms	microvolts root-mean-square			
mA	milliampere			
mm	millimeter			
ms	millisecond			
mV	millivolt			
nA	nanoampere			
ns	nanosecond			
nV	nanovolt			
Ω	ohm			
ppm	parts per million			
V	volt			



## **Document History Page**

Document Title: CY2XP311, 312.5 MHz LVPECL Clock Generator Document Number: 001-59931						
Rev.	ECN No.	Submission Date	Orig. of Change	Description of Change		
**	2897143	3/22/2010	KVM	New data sheet.		
*A	2915328	04/16/2010	KVM	Changed status from Preliminary to Final		
*B	3201150	03/21/2011	BASH	Added Ordering Code Definition. Updated Package Drawing and Dimensions. Added Acronyms and Units of Measure.		
*C	4335323	04/07/2014	CINM	Updated Package Drawing and Dimensions: spec 51-85093 – Changed revision from *C to *D. Updated in new template. Completing Sunset Review.		
*D	4570097	11/14/2014	CINM	Added related documentation hyperlink in page 1. Removed the prune part numbers CY2XP311ZXC and CY2XP311ZXCT in Ordering Information. Updated Figure 13 in Package Drawing and Dimensions (spec 51-85093 *D to *E).		
*E	5686604	04/06/2017	XHT	Updated to new template Completing sunset review		



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